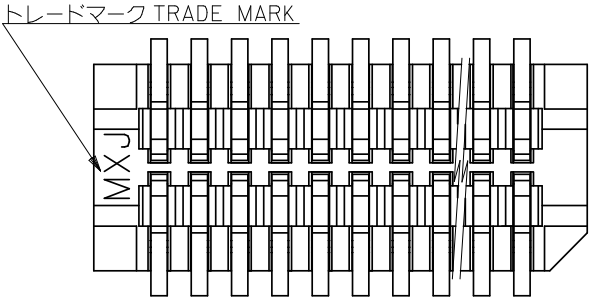
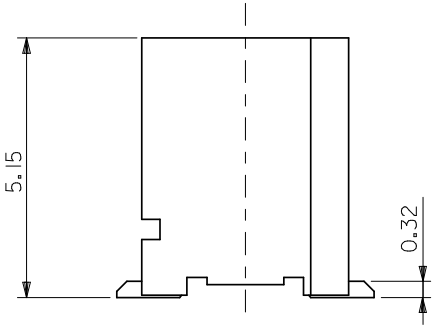
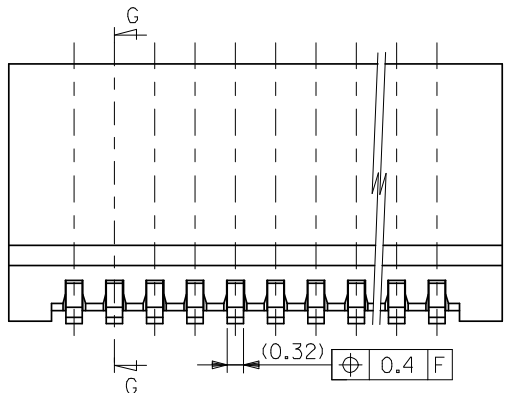


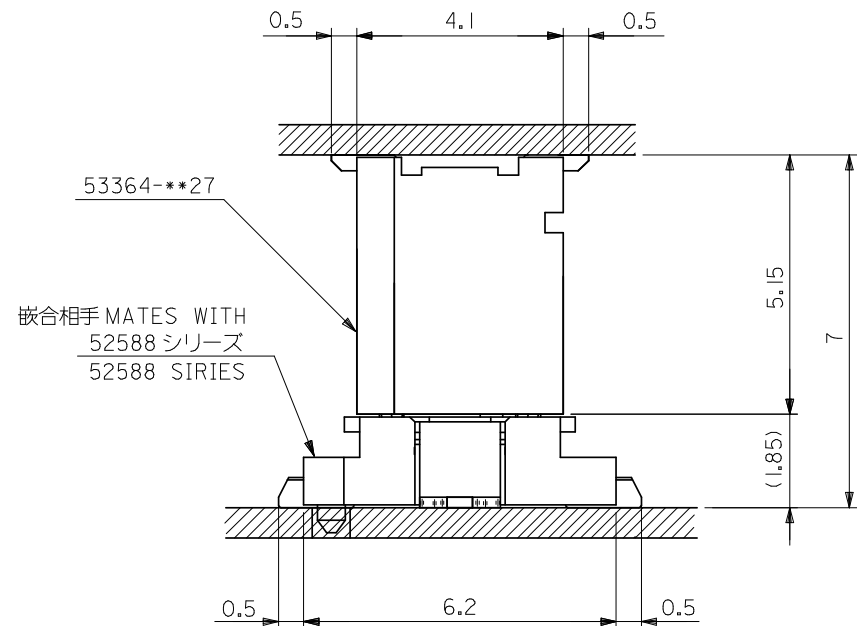
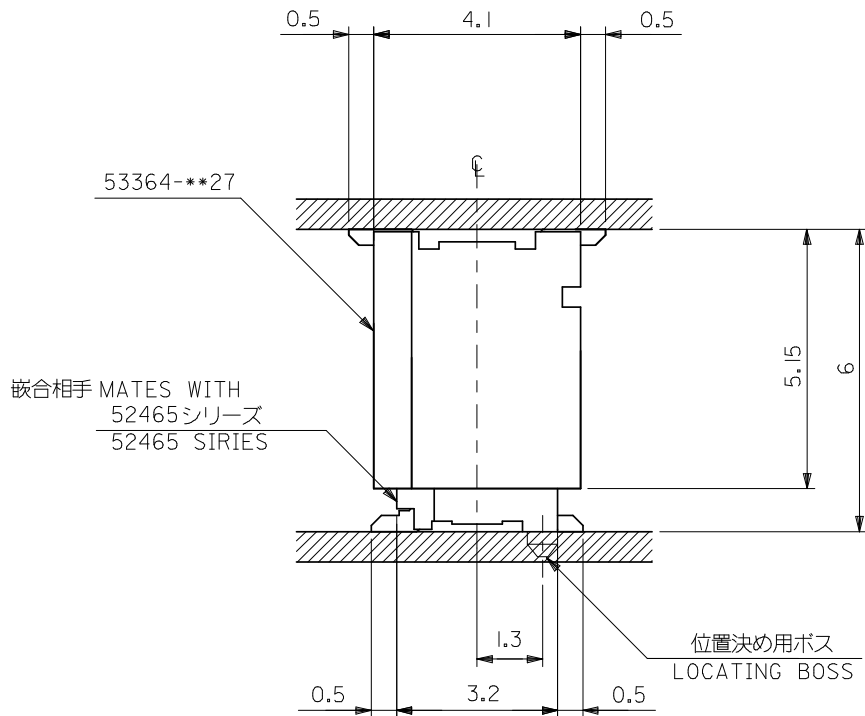
注記 NOTES

1. 嵌合相手: 52465, 52588 シリーズ  
MATES WITH: 52465, 52588 SERIES
- △ ウエハーの  $\phi$  から隣接するピンの  $\phi$  迄の位置を示す。  
SHOW POSITION FROM  $\phi$  OF WAFER TO  $\phi$  OF ADJACENT PINS.



0.8	13.8	12.9	11.2	53364-3027	30
0.8	5.8	4.9	3.2	53364-1027	10
D	C	B	A	MATERIAL NO.	極数 CKT.

REVISED EC NO: J2008-3931 DRWN: NAKAMURA 2008/05/26 CHKD: T. HARIYAMA 2008/05/26 APPR: NUKITA 2008/08/21	DESCRIPTION	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE	SCALE	DESIGN UNITS	THIRD ANGLE PROJECTION
		10 UNDER ±0.2		MM ONLY	---	METRIC	
		10 OVER 30 UNDER ±0.20		DRAWN BY	DATE	TITLE	
		30 OVER ±0.25		M. NAKAMURA		0.8 BOARD TO BOARD CONN. WAFER ASSY ST. SMT (WITHOUT BOSS) (1/2)	
A	REV	ANGULAR ±3 °	DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS	APPROVED BY	DATE	MATERIAL NO.	DOCUMENT NO.
		SEE TABLE		M. FUKUSHIMA		53364-3027	SD-53364-004
		SIZE A3	THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION				



嵌合状態図 (参考)  
MATED DRAWING (REF.)

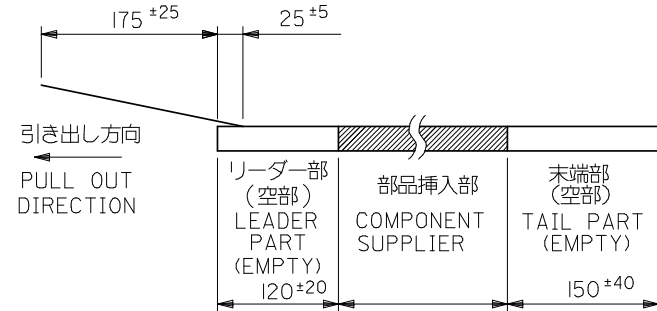
REVISED EC NO: J2008-3931 DRWN: NAKAMURA 2008/05/26 CHKD: T. HARIYAMA 2008/05/26 APPR: NUKITA 2008/08/21	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE ---	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION	
	10 UNDER	± ---	DRAWN BY M. NAKAMURA	DATE '95/7/17	TITLE 0.8 BOARD TO BOARD CONN. WAFER ASSY ST. SMT (WITHOUT BOSS) (2/2)			
	10 OVER 30 UNDER	± ---	CHECKED BY Y. M.	DATE '95/7/17	MOLEX INCORPORATED			
	30 OVER	± ---	APPROVED BY M. FUKUSHIMA	DATE '95/7/17	DOCUMENT NO. SD-53364-004		SHEET NO. 2 OF 2	
A	DESCRIPTION ANGULAR ± --- ° DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS	SIZE A3	SEE TABLE THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION					

注記 NOTES

1. 梱包数量：1000個/リール NUMBER OF CONNECTORS:1000PCS/REEL

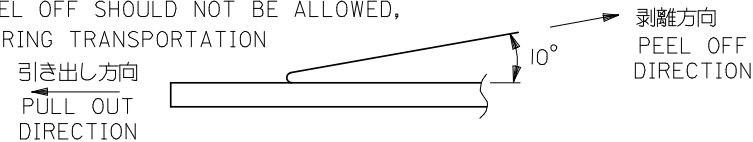
2. リードテープ長さ LEAD TAPE LENGTH

トップテープ TOP TAPE リーダー部 LEADER PART  
 トップテープ TOP TAPE 未接着部 NON-BONDED PART



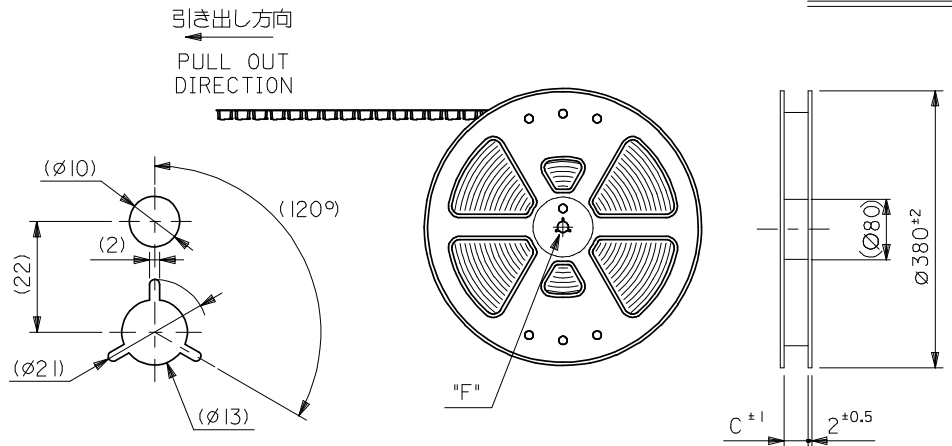
3. トップテープの剥離強度：(剥離方向は下図参照)  
 0.1N~0.7N(10.2gf~71.4gf) 尚、本規格値は、出荷時に適用。  
 (但し、輸送時に剥離が発生しない事。)

PEELING OFF FORCE OF TOP TAPE  
 0.1N~0.7N(10.2gf~71.4gf)(PEELING DIRECTION AS SHOWN IN FOLLOWING FIG.)  
 THIS REQUIREMENT SHOULD BE APPLIED AT SHIPMENT  
 PEEL OFF SHOULD NOT BE ALLOWED,  
 DURING TRANSPORTATION

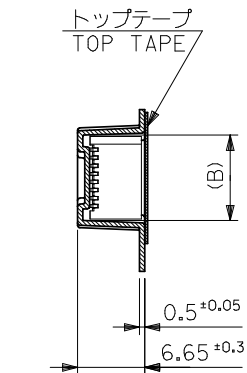


4. 材料 MATERIAL  
 キャリアテープ：ポリプロピレン (PP) CARRIER TAPE:POLYPROPYLENE  
 トップテープ：PET, PE, PEF TOP TAPE:PET,PE,PEF  
 リール：ポリスチレン (PS) REEL:POLYSTYREN(PS)  
 <リサイクル材を含む> <RECYCLE MATERIAL CONTAINED>

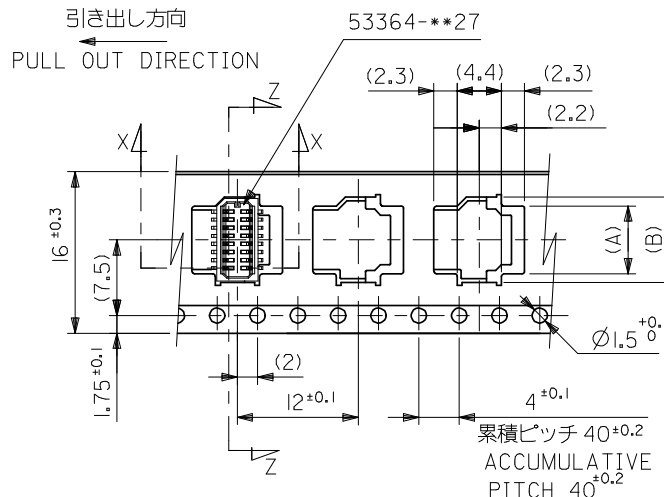
16	17.5	6.1	4.3	53364-1091	10
キャリアテープ幅 CARRIER TAPE WIDTH	C	(B)	(A)	MATERIAL NO.	極数 CIRCUIT
				MODEL NO.	53364-**91



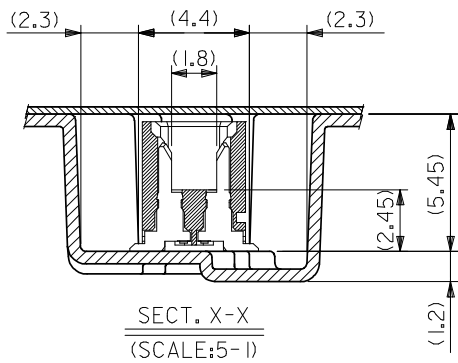
DETAIL "F"



SECT. Z-Z

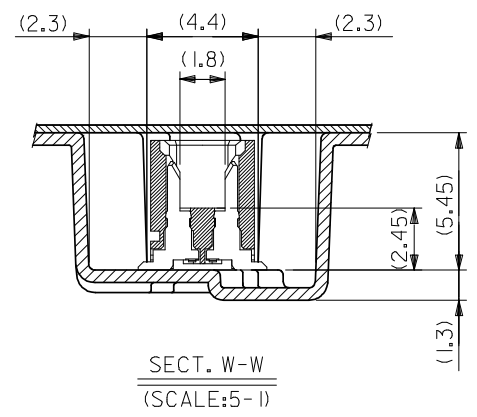
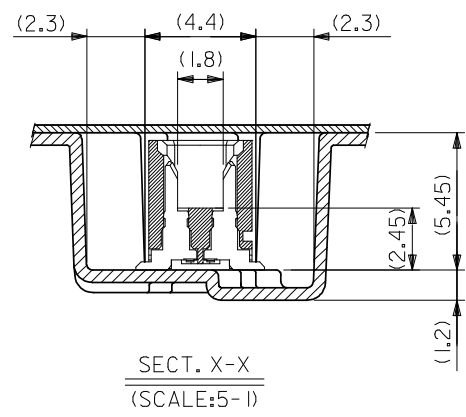
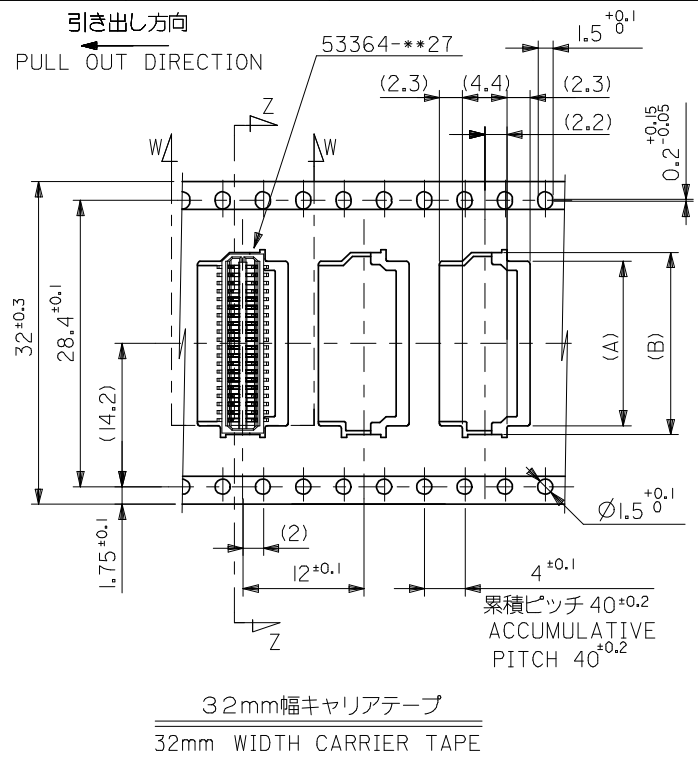
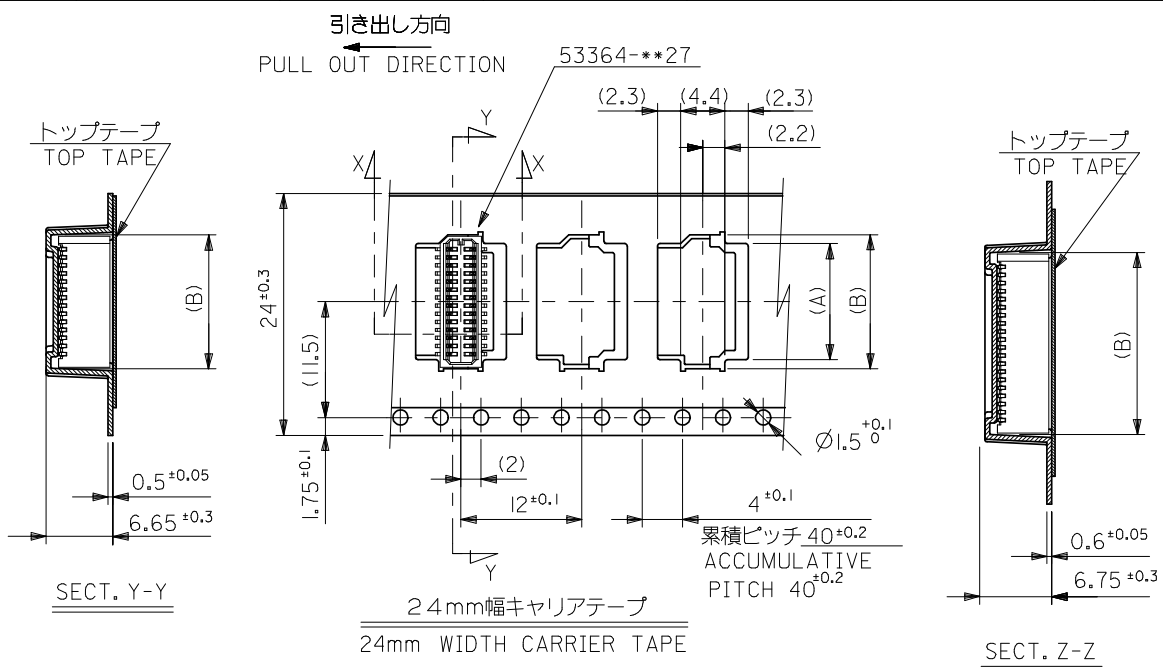


16mm幅キャリアテープ  
16mm WIDTH CARRIER TAPE



SECT. X-X  
(SCALE:5-1)

REVISED EC NO: J2008-3931 DRWN:NAKAMURA 2008/05/26 CHKD:T. HARIYAMA 2008/05/26 APPR:NUKITA 2008/08/21	DESCRIPTION	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE ---	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION		
		10 UNDER	± ---	DRAWN BY T. ITO	DATE '93/11/28	TITLE 0.8 BTB CONN WAFER ASSY ST SMT WITHOUT BOSS EMBTP PKG (1/2)				
		10 OVER 30 UNDER	± ---	CHECKED BY T. ITO	DATE '00/12/6	APPROVED BY M. FUKUSHIMA '00/12/6				
		30 OVER	± ---	MATERIAL NO. SEE TABLE		DOCUMENT NO. SD-53364-006		SHEET NO. 1 OF 2		
ANGULAR ± --- °		DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION						



24	25.5	14.1	12.3	53364-3091	30
キャリアテープ幅 CARRIER TAPE WIDTH	C	(B)	(A)	MATERIAL NO.	極数 CIRCUIT
				MODEL NO.	53364-***91

REVISED EC NO: J2008-3931 DRWN: MAKURAA 2008/05/26 CHKD: T. HARIYAMA 2008/05/26 APPR: NUKITA 2008/08/21	DESCRIPTION REV	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE ---	DESIGN UNITS METRIC	TITLE 0.8 BTB CONN WAFER ASSY ST SMT WITHOUT BOSS EMBTP PKG (2/2) MOLEX INCORPORATED SD-53364-006	SHEET NO. 2 OF 2
		10 UNDER	± ---	DRAWN BY T. ITO	DATE '93/1/28	THIRD ANGLE PROJECTION			
		10 OVER 30 UNDER	± ---	CHECKED BY T. ITO	DATE '00/12/6	SEE TABLE			
		30 OVER	± ---	APPROVED BY M. FUKUSHIMA	DATE '00/12/6	MATERIAL NO.			
ANGULAR ± --- °		DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		SIZE A3		THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION			